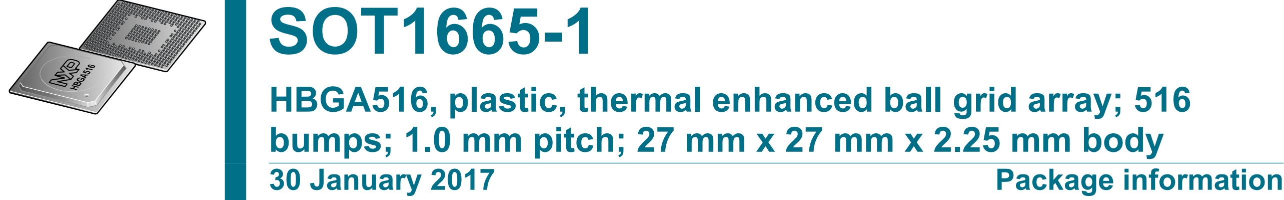

SOT1665-1

HBGA516, plastic, thermal enhanced ball grid array; 516 bumps; 1.0 mm pitch; 27 mm x 27 mm x 2.25 mm body

30 January 2017 — Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA516
Package type industry code	HBGA516
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	21-1-2016
Manufacturer package code	98ASA10789D

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	27	-	mm
E	package width		-	-	27	-	mm
A	seated height		-	-	2.25	2.55	mm
e	nominal pitch		-	-	1	-	mm
n_2	actual quantity of termination		-	-	516	-	

2. Package outline

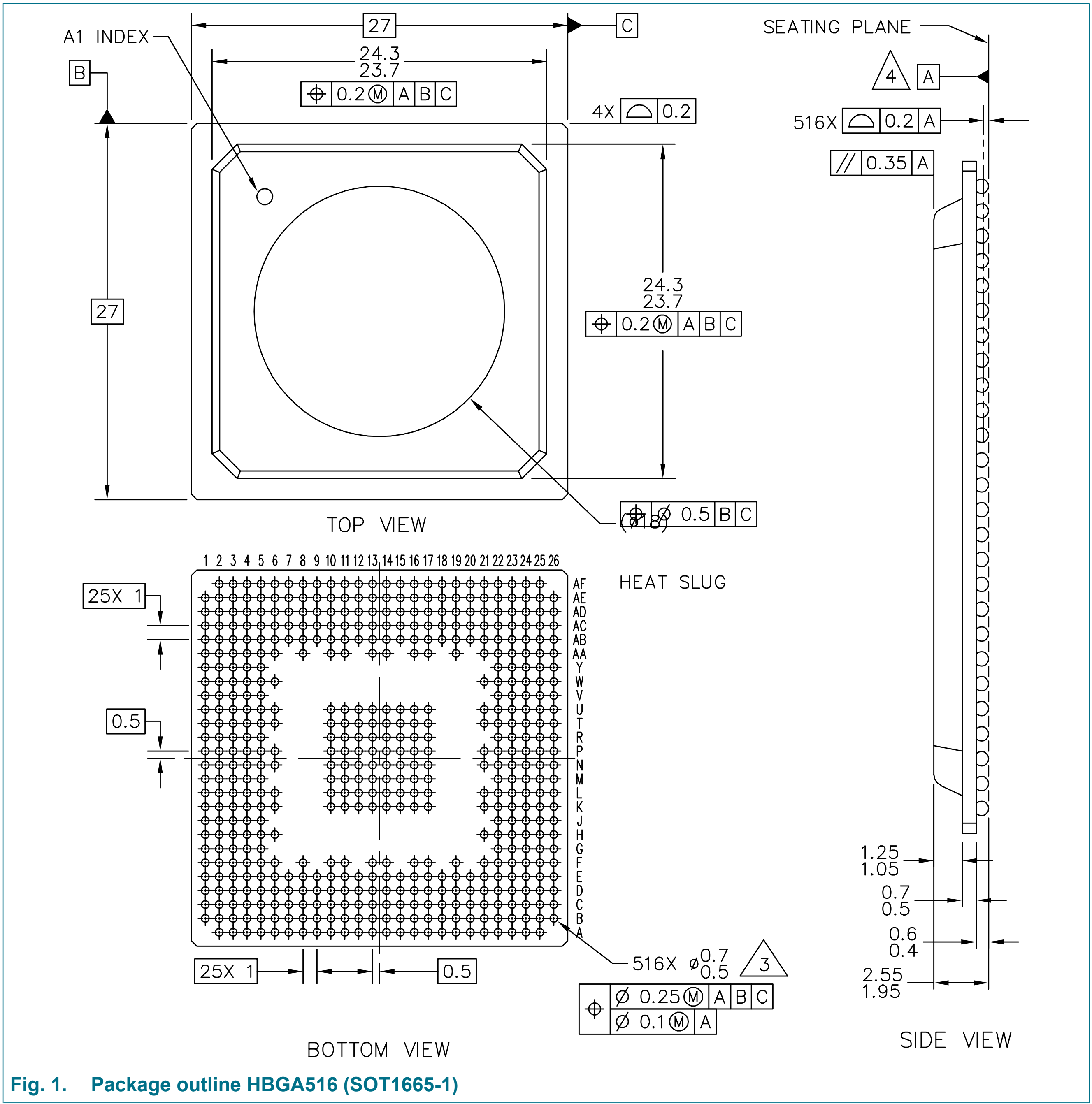

Fig. 1. Package outline HBGA516 (SOT1665-1)

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HBGA516, plastic, thermal enhanced ball grid array; 516 bumps; 1.0 mm pitch; 27 mm x 27 mm x 2.25 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M—1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PACKAGE CODE 5368 IS TO ACCOUNT FOR PGE AND THE BUILT—IN HEAT SPREADER.

Fig. 2. Package outline note HBGA516 (SOT1665-1)

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